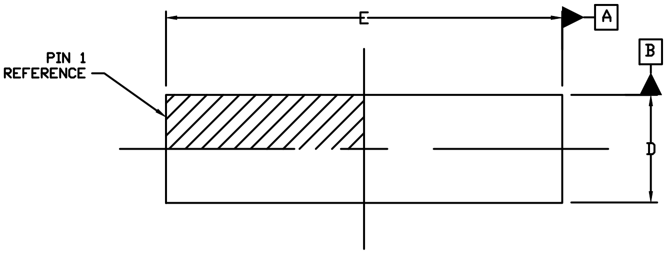
WLCSP30, 1.175x4.3x0.33

CASE 567WW
ISSUE O

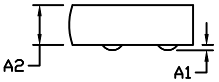
DATE 18 JUL 2018



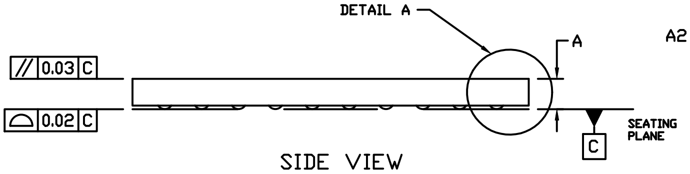
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

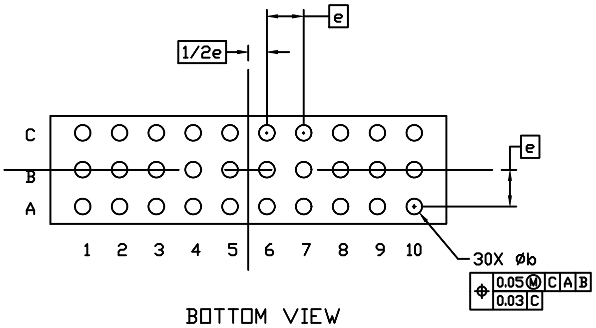


DETAIL A

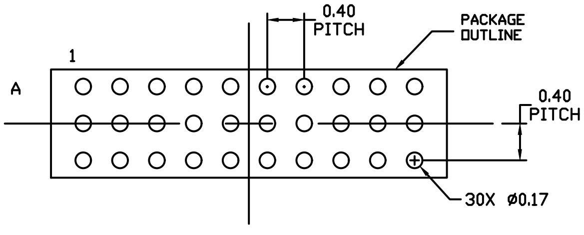


SIDE VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.31	0.33	0.35
A1	0.034	0.040	0.046
A2	0.278	0.290	0.303
b	0.15	0.17	0.19
D	1.15	1.175	1.20
E	4.275	4.30	4.325
e	0.40 BSC		



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*

XXXXXXXX
AWLYYWW

XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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